



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/465,492
Filing Date December 16, 1999
Inventor Segal et al.
Assignee Honeywell International Inc.
Group Art Unit 1742
Examiner Wilkins, III
Attorney's Docket No. 30-5004(4015)
Title: Sputtering Targets Formed From Cast Materials

INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.


Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: August 12, 2003

By: Jennifer J. Taylor
Jennifer J. Taylor, Ph.D.
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EV318283138

		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 30-5004(4015)		SERIAL NO. 09/465,492		
		LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Vladimir Segal et al.		
						FILING DATE December 16, 1999		GROUP 1742
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	5,171,379	12-1992	Kumar et al.				
	AB	5,194,101	03-1993	Worcester et al.				
	AC	6,521,173 B2	02-2003	Kumar et al.				
	AD	4,844,746	07-1989	Hormann et al.				
	AE							
	AF	US2002/0041819 A1	04-2002	Kumar et al.			Jul. 16, 2001	
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AM	62-297463	12-1987	Japan				
	AN	EP 0 902 102 A1	03-1999	EPO				
	AO	03-197640	08-1991	Japan				
	AP	EP 0 281 141 B2	06-2000	EPO				
	AQ							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AR		Susumu Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12 th International Plansee Seminar (1989) Topic 5: Ultrapure Refractory Metals, pp. 201-222.					
	AS		P. Ding et al., "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference, pp. 87-92.					
	AT		"Nickel, Cobalt and Their Alloys", pub. By ASM International, December 2000, pages 76, 230-234.					
EXAMINER				DATE CONSIDERED				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								